

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: YOSHIDA, et al

Serial No.: Rule 1.53(b) continuation of U.S. Patent  
Application Serial No. 09/581,814, filed June  
19, 2000

Filed: Herewith

For: ABRASIVE METHOD OF POLISHING TARGET MEMBER AND  
PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE

Group of parent: 3723

Examiner of parent: D. Nguyen

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents  
Washington, D.C. 20231

January 11, 2002

Sir:

Please amend the above-identified application, prior to  
examination thereof, as follows:

IN THE SPECIFICATION

Please amend the specification as follows:

Page 1, before line 1 "TECHNICAL FIELD", insert the  
following:

--CROSS REFERENCE TO RELATED APPLICATIONS

This application is a Continuation Application of  
Application Serial No. 09/581,814, filed June 19, 2000.--

IN THE CLAIMS

Please cancel Claims 2 - 25 and 27 - 28.

Please amend Claims 26 and 29 as follows:

26. (amended) A method of polishing a target member,  
comprising polishing a target member by use of the abrasive of  
Claim 1.

29. (amended) A process for producing a semiconductor device,  
comprising the step of polishing a semiconductor chip on which  
a silica film has been formed, by use of the abrasive of Claim  
1.

REMARKS

This application is a Continuation Application under 37 CFR 1.53(b) of Application Serial No. 09/581,814, filed June 19, 2000. The specification is amended to include a cross-reference to the prior application. Claims 2 - 29 are canceled.

Applicants intend to file a Supplemental Preliminary Amendment to further define the invention. If such an Supplemental Amendment has not been filed by the time the Examiner takes up this case for examination, Applicants respectfully request that the Examiner notify the Applicants before taking action thereon.

Kindly charge any additional fees due, or credit overpayment of fees, to Deposit Account No. 01-2135. (File No. 566.38683X00).

Respectfully submitted,

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RTW/RTW

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26. (amended) A method of polishing a target member,  
comprising polishing a target member by use of the abrasive  
~~according to any one of claims 1 to 25 of Claim 1.~~

29. (amended) A process for producing a semiconductor device,  
comprising the step of polishing a semiconductor chip on which  
a silica film has been formed, by use of the abrasive  
~~according to any one of claims 1 to 25 of Claim 1.~~